Low-Voltage CMOS Octal D-Type Flip-Flop

With 5 V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The MC74LCX374 is a high performance, non-inverting octal D-type flip-flop operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX374 inputs to be safely driven from 5 V devices.

The MC74LCX374 consists of 8 edge-triggered flip-flops with individual D-type inputs and 3-state true outputs. The buffered clock and buffered Output Enable (OE) are common to all flip-flops. The eight flip-flops will store the state of individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the \overline{OE} LOW, the contents of the eight flip-flops are available at the outputs. When the \overline{OE} is HIGH, the outputs go to the high impedance state. The \overline{OE} input level does not affect the operation of the flip-flops.

Features

- Designed for 2.3 to 3.6 V V_{CC} Operation
- 5 V Tolerant Interface Capability With 5 V TTL Logic
- Supports Live Insertion and Withdrawal
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0 \text{ V}$
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance:
 - ♦ Human Body Model >2000 V
 - ♦ Machine Model >200 V
- These Devices are Pb-Free and are RoHS Compliant



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MARKING DIAGRAMS

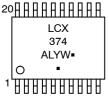


SOIC-20 WB **DW SUFFIX CASE 751D**





TSSOP-20 **DT SUFFIX CASE 948E**





SOEIAJ-20 **M SUFFIX CASE 967**



= Assembly Location

L. WI = Wafer Lot = Year W. WW = Work Week G or • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

1

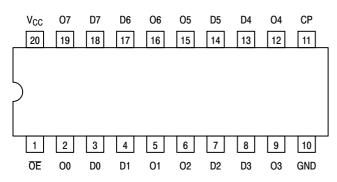


Figure 1. Pinout: 20-Lead (Top View)

PIN NAMES

Pins	Function	
ŌĒ	Output Enable Input	
CP	Clock Pulse Input	
D0-D7 Data Inputs		
00-07	3-State Outputs	

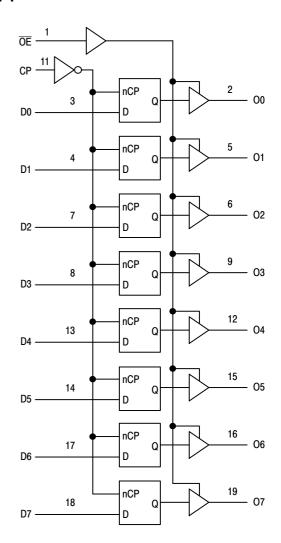


Figure 2. LOGIC DIAGRAM

TRUTH TABLE

INPUTS		INPUTS		
ŌĒ	СР	Dn	On	OPERATING MODE
L L	↑	l h	L H	Load and Read Register
L	1	Х	NC	Hold and Read Register
Н	1	X	Z	Hold and Disable Outputs
H H	<u>†</u>	l h	Z Z	Load Internal Register and Disable Outputs

High Voltage Level Н

h High Voltage Level One Setup Time Prior to the Low-to-High Clock Transition

L Low Voltage Level

Low Voltage Level One Setup Time Prior to the Low-to-High Clock Transition 1

No Change, State Prior to Low-to-High Clock Transition High or Low Voltage Level and Transitions are Acceptable NC = X Z

High Impedance State Low-to-High Transition

1 Not a Low-to-High Transition; For I_{CC} Reasons, DO NOT FLOAT Inputs

MAXIMUM RATINGS

Symbol	Parameter	Condition	Value	Units
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \le V_{I} \le +7.0$	V
Vo	DC Output Voltage	Output in 3-State	$-0.5 \le V_0 \le +7.0$	V
		(Note 1)	$-0.5 \le V_O \le V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current	V _I < GND	-50	mA
I _{OK}	DC Output Diode Current	V _O < GND	-50	mA
		V _O > V _{CC}	+50	mA
Io	DC Output Source/Sink Current		±50	mA
Icc	DC Supply Current Per Supply Pin		±100	mA
I _{GND}	DC Ground Current Per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	2.0 1.5	3.3 3.3	3.6 3.6	V
VI	Input Voltage	0		5.5	V
Vo	Output Voltage (HIGH or LOW State) (3-State)	0		V _{CC} 5.5	V
I _{OH}	HIGH Level Output Current, V _{CC} = 3.0 V – 3.6 V			-24	mA
l _{OL}	LOW Level Output Current, V _{CC} = 3.0 V - 3.6 V			24	mA
I _{OH}	HIGH Level Output Current, V _{CC} = 2.7 V - 3.0 V			-12	mA
l _{OL}	LOW Level Output Current, V _{CC} = 2.7 V - 3.0 V			12	mA
T _A	Operating Free-Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8 V to 2.0 V, V_{CC} = 3.0 V	0		10	ns/V

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX374DWR2G	SOIC-20 WB (Pb-Free)	1000 Tape & Reel
MC74LCX374DTR2G	TSSOP-20*	2500 Tape & Reel
MC74LCX374MELG	SOEIAJ-20 (Pb-Free)	2000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{1.} Output in HIGH or LOW State. Io absolute maximum rating must be observed.

^{*}This package is inherently Pb-Free.

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°C	to +85°C	
Symbol	Characteristic	Condition	Min	Max	Units
V _{IH}	HIGH Level Input Voltage (Note 2)	2.7 V ≤ V _{CC} ≤ 3.6 V	2.0		V
V _{IL}	LOW Level Input Voltage (Note 2)	2.7 V ≤ V _{CC} ≤ 3.6 V		0.8	V
V _{OH}	HIGH Level Output Voltage	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OH} = -100 \mu\text{A}$	V _{CC} - 0.2		V
		$V_{CC} = 2.7 \text{ V}; I_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -18 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V}; I_{OH} = -24 \text{ mA}$	2.2		
V _{OL}	LOW Level Output Voltage	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; \text{I}_{OL} = 100 \mu\text{A}$		0.2	٧
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 16 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
l _l	Input Leakage Current	$2.7 \text{ V} \le \text{V}_{CC} \le 3.6 \text{ V}; 0 \text{ V} \le \text{V}_{I} \le 5.5 \text{ V}$		±5.0	μΑ
l _{OZ}	3-State Output Current	$2.7 \le V_{CC} \le 3.6 \text{ V}; \text{ 0 V} \le V_{O} \le 5.5 \text{ V};$ $V_{I} = V_{IH} \text{ or V}_{IL}$		±5.0	μΑ
I _{OFF}	Power-Off Leakage Current	V _{CC} = 0 V; V _I or V _O = 5.5 V		10	μΑ
I _{CC}	Quiescent Supply Current	$2.7 \le V_{CC} \le 3.6 \text{ V}; V_I = \text{GND or } V_{CC}$		10	μΑ
		$2.7 \le V_{CC} \le 3.6 \text{ V}$; $3.6 \le V_I \text{ or } V_O \le 5.5 \text{ V}$		±10	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	$2.7 \le V_{CC} \le 3.6 \text{ V}; \text{ V}_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

^{2.} These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS (t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω)

			Limits				
			T _A = -40°C to +85°C				
			V _{CC} = 3.0	V to 3.6 V	V _{CC} =	2.7 V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Units
f _{max}	Clock Pulse Frequency	1	150				MHz
t _{PLH} t _{PHL}	Propagation Delay CP to O _n	1	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t _{PZH} t _{PZL}	Output Enable Time to HIGH and LOW Levels	2	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t _{PHZ} t _{PLZ}	Output Disable Time from HIGH and LOW Levels	2	1.5 1.5	7.5 7.5	1.5 1.5	8.5 8.5	ns
ts	Setup Time, HIGH or LOW Dn to CP	1	2.5		2.5		ns
t _h	Hold Time, HIGH or LOW D _n to CP	1	1.5		1.5		ns
t _w	CP Pulse Width, HIGH or LOW	3	3.3		3.3		ns
t _{OSHL} t _{OSLH}	Output-to-Output Skew (Note 3)			1.0 1.0			ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

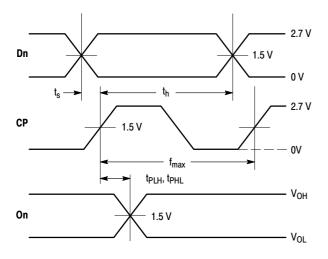
DYNAMIC SWITCHING CHARACTERISTICS

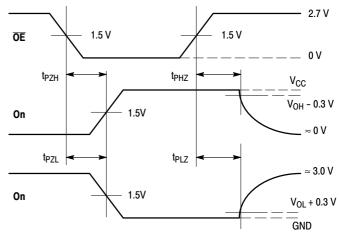
			T _A = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Units
V _{OLP}	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		٧
V _{OLV}	Dynamic LOW Valley Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$		0.8		V

^{4.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

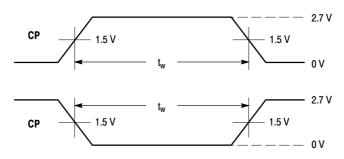
Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	25	pF





WAVEFORM 1 – PROPAGATION DELAYS, SETUP AND HOLD TIMES $t_R=t_F=2.5 \ ns, \ 10\% \ to \ 90\%; \ f=1 \ MHz; \ t_W=500 \ ns$

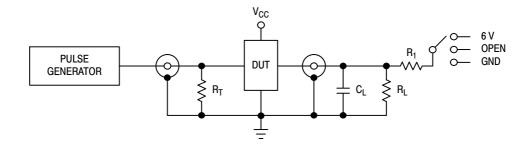
WAVEFORM 2 – OUTPUT ENABLE AND DISABLE TIMES $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$



WAVEFORM 3 – PULSE WIDTH

 t_R = t_F = 2.5 ns (or fast as required) from 10% to 90%; Output requirements: V_{OL} \leq 0.8 V, V_{OH} \geq 2.0 V

Figure 3. AC Waveforms

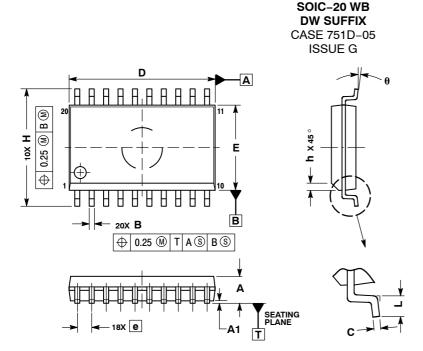


TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6 V
Open Collector/Drain t _{PLH} and t _{PHL}	6 V
t _{PZH} , t _{PHZ}	GND

 C_L = 50 pF or equivalent (Includes jig and probe capacitance) R_L = R_1 = 500 Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

PACKAGE DIMENSIONS



NOTES:

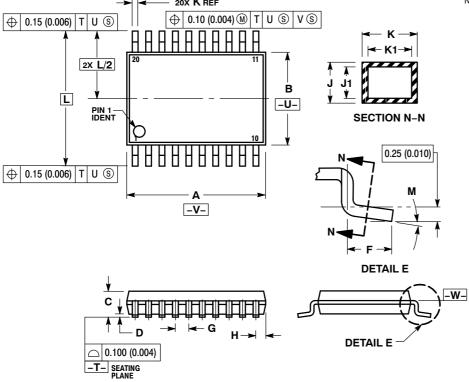
- NOTES:

 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS			
DIM	MIN MAX			
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
С	0.23	0.32		
D	12.65	12.95		
E	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
θ	0°	7 °		

PACKAGE DIMENSIONS

TSSOP-20 **DT SUFFIX** CASE 948E-02 ISSUE C



NOTES:

- DTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

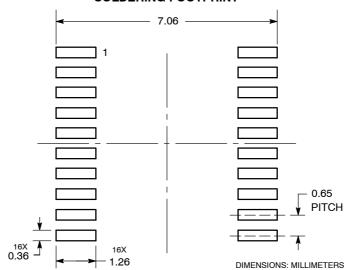
 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED A 15 (AGAPE PER SUBJECT OF THE PROPERTY SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER
- SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W-.

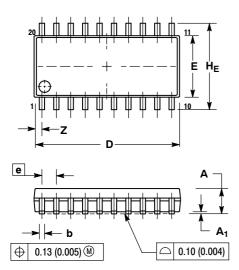
	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20	-	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.27	0.37	0.011	0.015
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252 BSC	
М	0°	8°	0°	8°

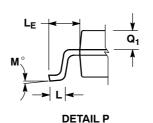
SOLDERING FOOTPRINT

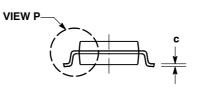


PACKAGE DIMENSIONS

SOEIAJ-20 **M SUFFIX** CASE 967-01 **ISSUE A**







NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- B. DIMENSIONS D AND E DO NOT INCLUDE
 MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.

 DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.15	0.25	0.006	0.010
D	12.35	12.80	0.486	0.504
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0°	10°	0 °	10°
Q_1	0.70	0.90	0.028	0.035
Z		0.81		0.032

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